



The banner features a dark blue background with a circuit board pattern on the left and various technology-related icons on the right. The text is centered and uses a mix of white, yellow, and orange colors for emphasis.

VLSI Technology, Systems and Applications
April 18-21, 2022 Hsinchu, Taiwan
Call for Papers
Submission Deadline:
~~November 1, 2021~~
extended to November 10, 2021

Logos for VLSI (SINCE 1983), ITRI, and IEEE are present.

The 2022 International Symposium on VLSI Technology Systems and Applications (**VLSI-TSA**) will be held on April 18-21, 2022 at the Ambassador Hotel, Hsinchu, Taiwan. The symposium has been kicked-off since 1983. It is a premiere conference in Taiwan and received up to 1,000 participants every year. It provides a unique opportunity to network with VLSI leading experts worldwide. Original and unpublished papers on all aspects of advanced VLSI technology and applications are solicited.

Hsinchu City: The well-known Taiwan's Silicon Valley is based with clusters of world-class high Tech. IC manufacturing and design. It is one-hour driving distance from Taipei, 40 minutes from the airport. Industry attendees may take this opportunity to visit Science Park business unit and academia attendees may visit major universities/institutes of Taiwan, either in Hsinchu, or down to the south by the high speed train within one hour.

COVID-19 Watch: 2022 VLSI-TSA is planned for an in-person/on-site event. In the meantime, we will keep Hybrid meeting (same as 2021) if COVID-19 still keeps a threat to the convention, i.e., arranging overseas presenters to provide a pre-recorded video for presentation on condition that they render into travel restrictions.

[Paper submission click here](#)

Papers in the following scope are solicited:

- Front-end CMOS and Foundry technology
- Standalone memory: DRAM, FLASH, emerging memory technology
- Ultra-low power CMOS and embedded memory
- Advanced process modules: e.g. gate stack, junction, strain/channel engineering, low-R contact, low-C spacer/ILD, interconnect technology, ALE and selective deposition, etc.
- Advanced packaging and 2.5D/3D Integration
- TFT and organic electronics
- MEMS, imagers and sensors
- Power and analog IC device and technology
- Photonics and beyond CMOS Technology
- RF & THz process, device and integration technology
- Energy harvesting technology
- Wearable and IoE enabling technologies
- Quantum phenomena and information technologies

- Nano-patterning: multiple patterning, directed self-assembly, EUV, etc.
- Advanced CMOS process and devices: Ge, SiGe, III-V, FinFET, GAAFET, low-dimensional materials and devices, 2D and nanowire devices
- BEOL compatible devices for 3D integration
- Material, Process and device modeling
- Reliability physics, characterization and test
- Neuromorphic devices and materials for brain-inspired computing
- Device/circuit technologies for AI deep learning applications
- Advanced manufacturing technology, metrology and yield

Paper Submission(s) Guideline:

- The paper should be written in English.
- Submissions of the [2-page camera-ready manuscript](#) in **pdf format**, including figures and tables.
- In addition to the camera-ready manuscript, the submission should include a **100~200 Word** abstract.
- Upon acceptance of your paper, an electronic IEEE copyright form (eCF) is compulsory and must be submitted online via the [Paper Submission site](#). For more information about IEEE Copyright, please refer to the [IEEE Copyright Policy](#) site.
- No-show papers will not be included in the symposium proceedings and will not be submitted to the IEEE Xplore database.
- All paper presenters are required to register for the symposium by **February 28, 2022** and present at the symposium.

Important Dates:

- Paper Submission Deadline **EXTENDED to November 10, 2021 23:59 (Taipei time)**
- Acceptance Notification **December 31, 2021**
- Author Registration Deadline **February 28, 2022**

Student Subsidy:

[Financial support](#) for full-time overseas student authors is available.

Up to 65% discount for all students on registration fee.

Best Student Paper Award:

The selection will be based on the evaluation by members of technical committees of students' papers, as well as their oral presentations during the conference.

The [Best Student Paper Award](#) will be granted to the winning students at the next conference.

Late News Papers: (Submission Deadline : Jan 15, 2022)

A very limited number of high quality Late News Papers will be accepted.

[Late News Papers](#) are not eligible for the best student paper award.

For further information, please contact:

Caroline Huang
Symposium Secretariat
Email: vsitsa@itri.org.tw
Website: <https://expo.itri.org.tw/2022vsitsa>

General Chairs

Toshiro Hiramoto, The University of Tokyo
Chih-I Wu, Industrial Technology Research Institute

Technical Program Chairs

Peide Ye, Purdue University
Wei-Chung Lo, Industrial Technology Research Institute